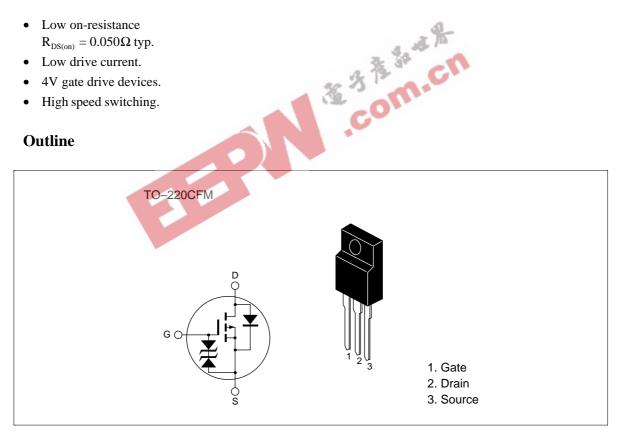
Silicon P Channel MOS FET High Speed Power Switching



ADE-208-646A (Z) 2nd. Edition Jun 1998

Features





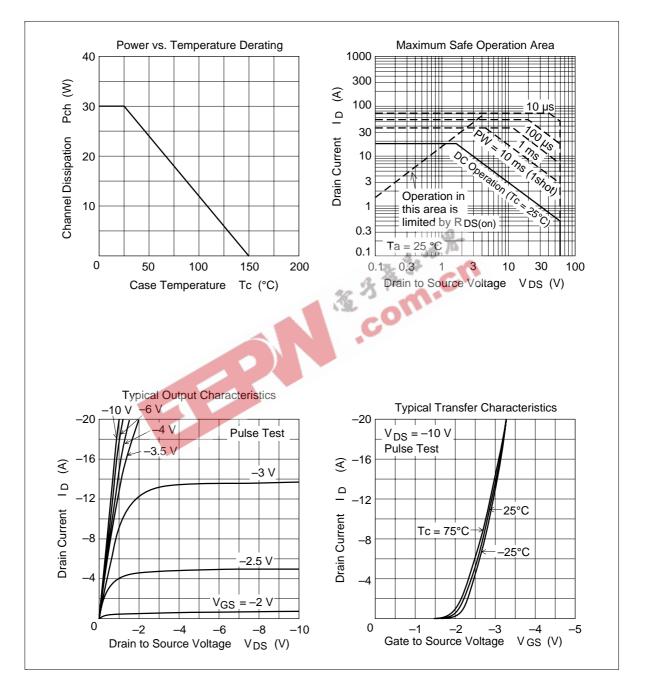
Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit			
Drain to source voltage	V _{DSS}	-60	V			
Gate to source voltage	V _{GSS}	±20	V			
Drain current	I _D	-18	A			
Drain peak current	Note1 D(pulse)	-72	A			
Body-drain diode reverse drain current	I _{DR}	-18	A			
Avalanche current	I AP Note3	-18	A			
Avalanche energy	E _{AR} ^{Note3}	27	mJ			
Channel dissipation	Pch Note2	30	W			
Channel temperature	Tch	150	°C			
Storage temperature	Tstg	-55 to +150	°C			
Note: 1. $PW \le 10\mu s$, duty cycle $\le 1 \%$						
2. Value at $T_c = 25^{\circ}C$						
Note: 1. $PW \le 10\mu s$, duty cycle $\le 1 \%$ 2. Value at Tc = 25°C 3. Value at Tch = 25°C, $Rg \ge 50 \Omega$						
Electrical Characteristics (Ta = 25°C)						
ltem Syr	mbol Min Typ	Max Unit Tes	t Conditions			

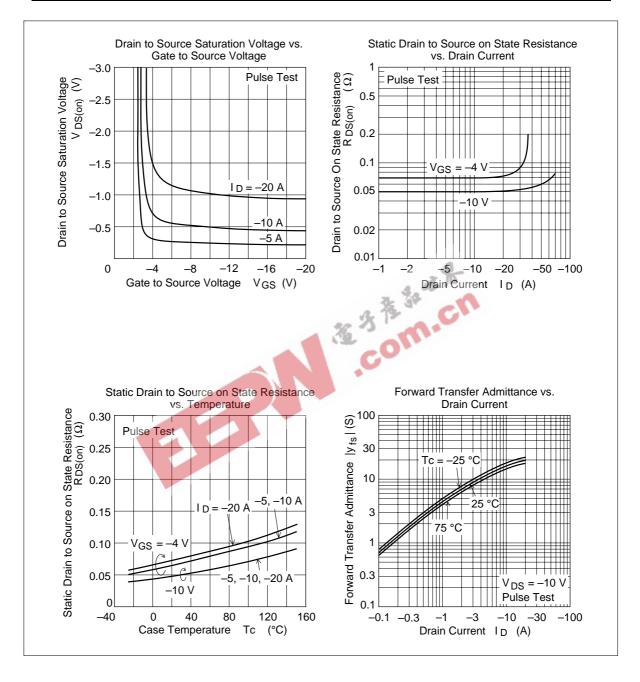
Electrical Characteristics ($Ta = 25^{\circ}C$)

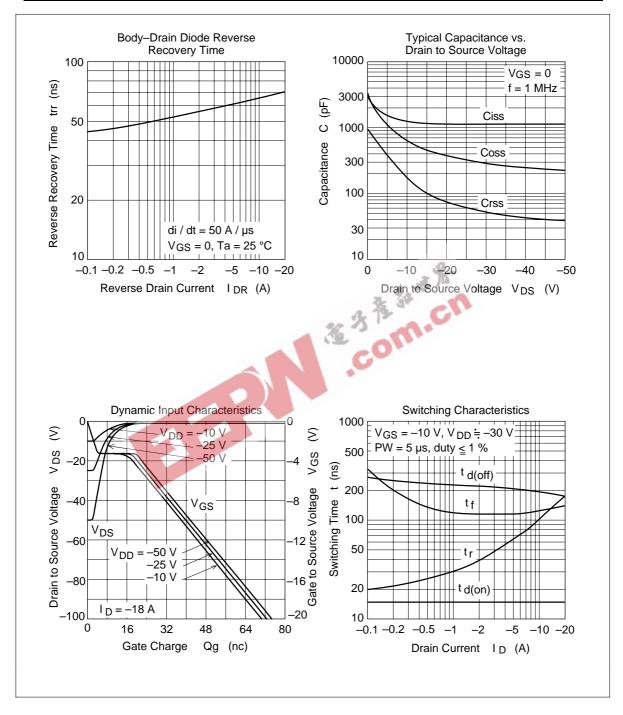
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DSS}	-60	_	_	V	$I_{\rm D} = -10 {\rm mA}, V_{\rm GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±20			V	$I_{g} = \pm 100 \mu A, V_{DS} = 0$
Zero gate voltege drain current	IDSS			-10	μA	$V_{\rm DS} = -60 \text{ V}, V_{\rm GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μA	$V_{GS} = \pm 16V, V_{DS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	-1.0		-2.0	V	$I_{\rm D} = -1$ mA, $V_{\rm DS} = -10$ V
Static drain to source on state	R _{DS(on)}		0.050	0.065	Ω	$I_{\rm D} = -9A, V_{\rm GS} = -10V^{\rm Note4}$
resistance	R _{DS(on)}	_	0.070	0.110	Ω	$I_{\rm D}$ = -9A, $V_{\rm GS}$ = -4V ^{Note4}
Forward transfer admittance	y _{fs}	10	16	_	S	$I_{\rm D} = -9A, V_{\rm DS} = -10V^{\rm Note4}$
Input capacitance	Ciss		1300		pF	$V_{DS} = -10V$
Output capacitance	Coss	_	650	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	180	_	pF	f = 1MHz
Turn-on delay time	t _{d(on)}		14		ns	$V_{GS} = -10V, I_{D} = -9A$
Rise time	t,	—	95	_	ns	R_ =3.33Ω
Turn-off delay time	t _{d(off)}		190		ns	_
Fall time	t _f		135		ns	_
Body-drain diode forward voltage	V_{DF}	_	-1.0	_	V	$I_{\rm F} = -18$ A, $V_{\rm GS} = 0$
Body–drain diode reverse recovery time	t _{rr}		70	_	ns	$I_{F} = -18A, V_{GS} = 0$ diF/ dt =50A/µs

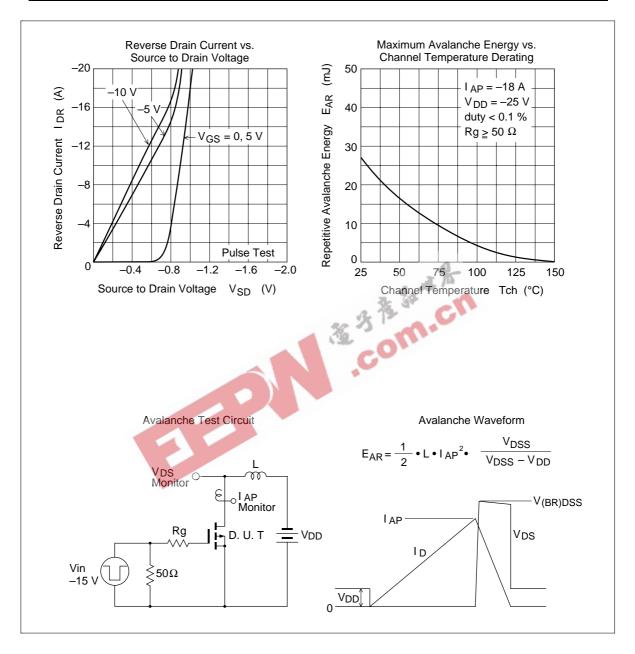
Note: 4. Pulse test

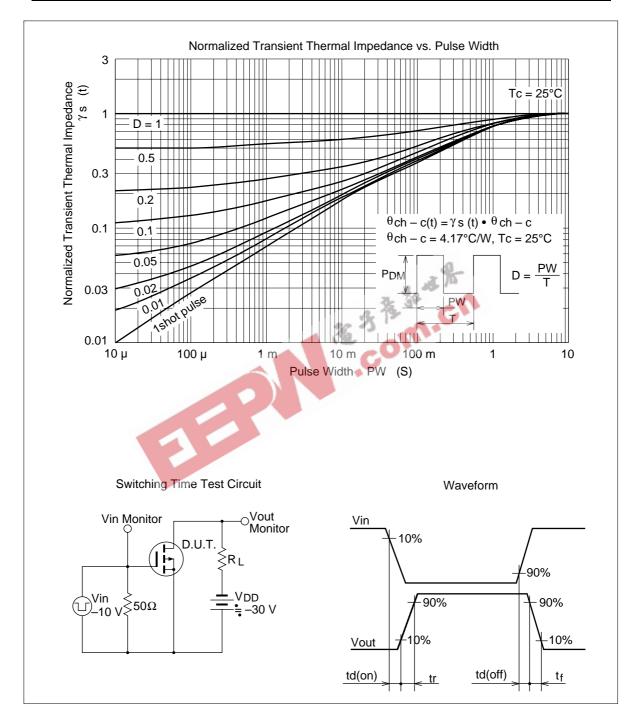


Main Characteristics

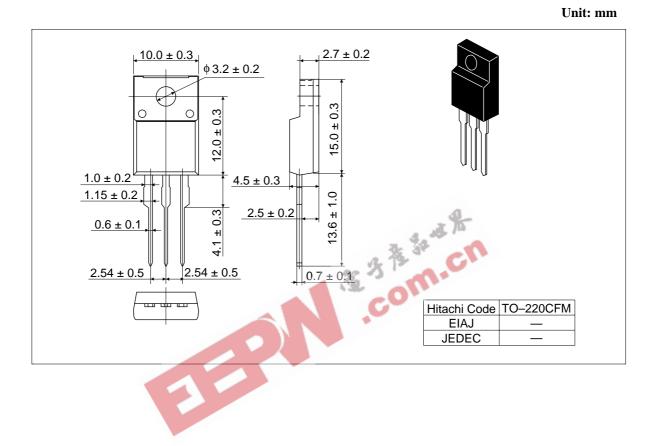








Package Dimensions



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